



# Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model  
[List multiple models if applicable.]

HP ONE zMod fAvayaSBC pwrby AcmePacket / J9486A

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		

Components, parts and materials containing radioactive substances		
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Drivers	T-6, T-8, T-10, Box type
Phillips Screw Driver	
Description #3	
Description #4	
Description #5	




## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the CF card on the PCA. Pic.1
2. Using the Phillips screw driver, removes the 4 Phillips screw attaching the hard drive to the PCA. Pic.2
3. Remove the 4 screws that attached the brackets to the hard drive using a T-8 screwdriver. Pic.3
4. Remove the 2 dust covers. Pic 4
5. Remove the small PCA by removing the 4 screws. Pic 5
6. Remove the 4 standoffs using a Boxtype Torx screwdriver. Pic 6
7. Remove the upperdeck PCA by removing the 5 screws. Follow the sequence indicated. Pic 7
8. Remove the upper deck PCA from the lower deck PCA by removing the cable from the lower deck connector. Pic 8
9. Remove the cable from the upper deck PC
10. Remove the remaining 4 standoffs on the upper deck PCA. Pic 9
11. Remove the plunger that attached the Com-E module into the PCA using a T-10 screwdriver. Refer to Pic.10 (d)
12. Remove the 4 standoffs that attached the Com-E module onto the PCA using the Boxtype Torx screwdriver. Refer to Pic.10 (e)
13. Remove another 1 standoff, using the Boxtype Torx screwdriver. Refer to Pic.10 (f)
14. Remove the Com-E module
15. Remove the 2 metal covers on the bulkhead by removing the 2 screws. Pic 11.
16. Remove the bulkhead by removing the 5 screws securing the bulkhead onto the PCA. Remove 3 screws using the T-6 screwdriver [Pic.12 (g)] and another 2 screws using the T-10 screwdriver [Pic.12 (h)]
17. Remove two screws and springs on the bulkhead. Refer to Pic.13
18. Remove the 2 standoff on the lower deck PCA. Pic 14
19. Remove the 4 screws that attached the heatsink onto the PCA using the T-10 Torx screwdriver. Refer to Pic.15 (j)
20. Remove the guide pin by using a T-10 Torx screwdriver to remove the 1 screw that attached the guide pin to the PCA. Refer to Pic.15 (k)
21. Remove the 3 standoffs via bottom 3 screws using the T-10 screwdriver. Refer to Pic.15 (m)
22. Remove the 5 standoffs via bottom 5 screws using the T-8 screwdriver. Refer to Pic.16 (n)
23. Remove the solder-anchor heatsink (towards right of PCA when looking from front) by releasing the catch from the 2 anchors. Refer to Pic.17

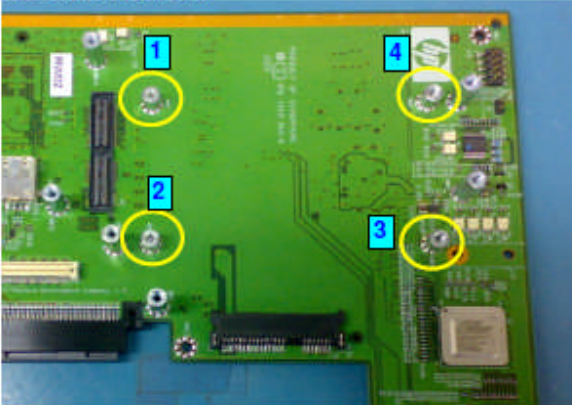
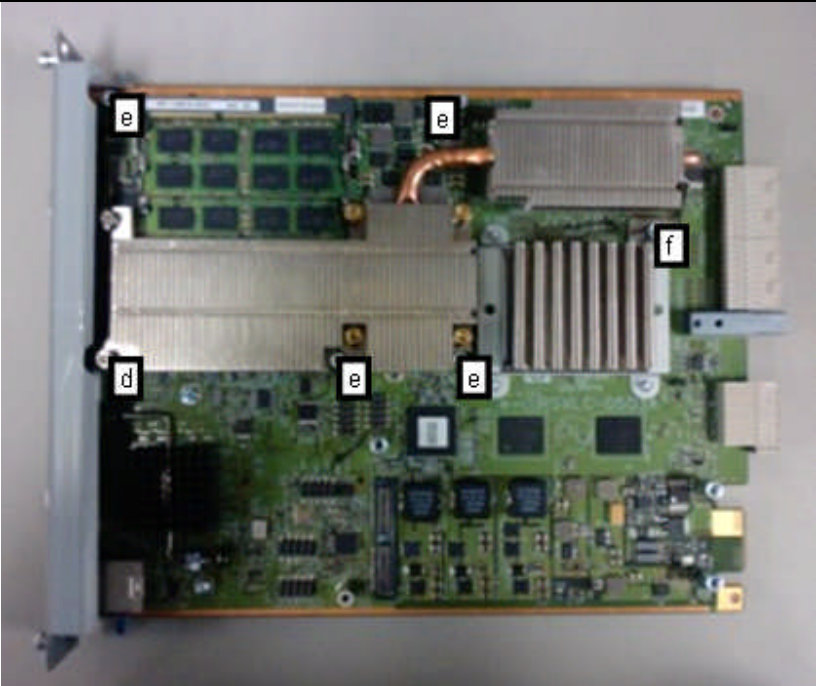
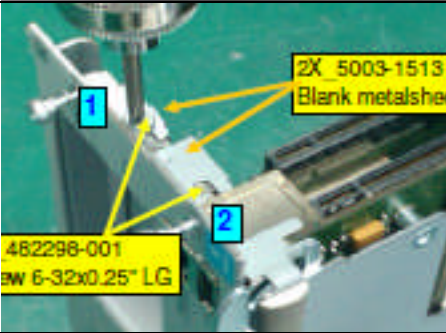
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

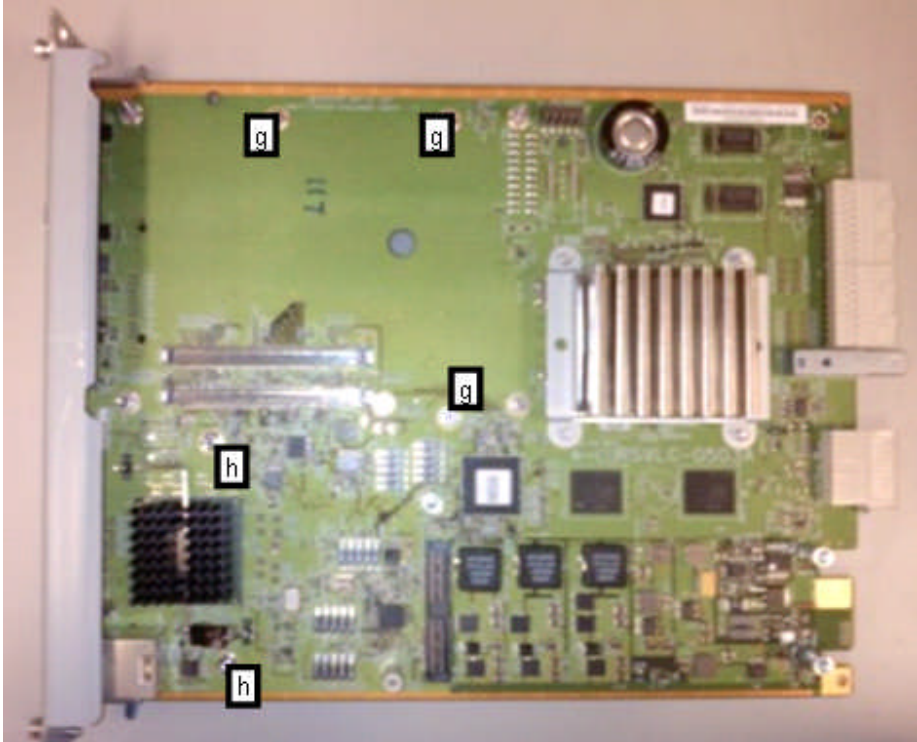
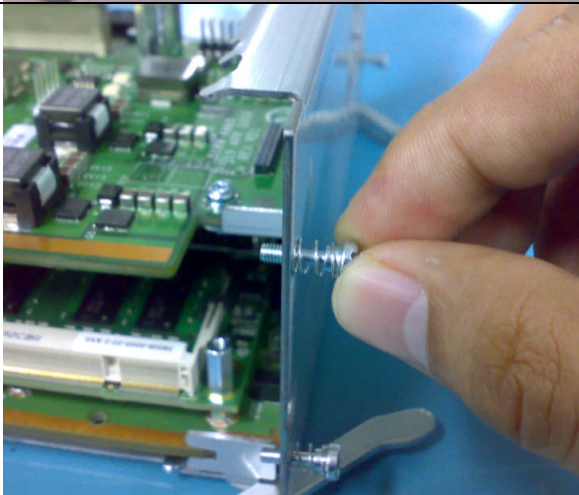
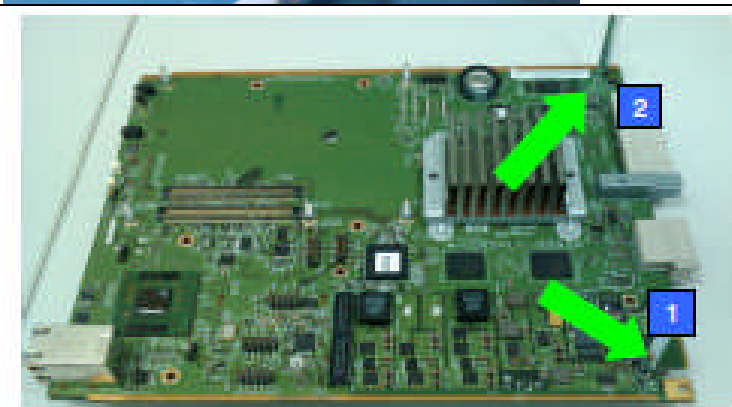
Pic	Illustration
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